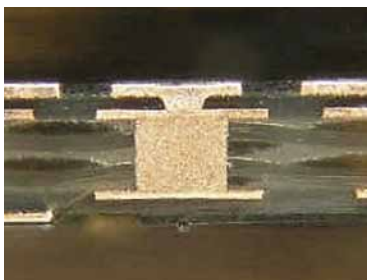


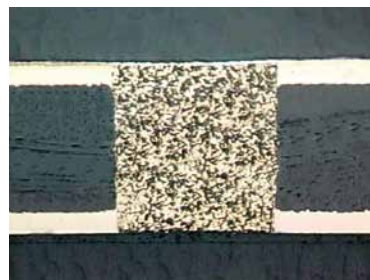
# Conductive Copper Paste

for via filling of Non-Copper Plating Via

## DD paste **AE2217 / AE1244**



1-2-1 Stacked Via type Build-up Core PCB

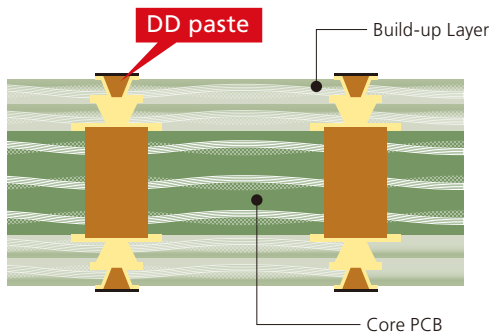


Direct Nickel / Gold plating

### Features

- ▶ Superior conductivity ( $1.0 \times 10^{-4} \Omega \cdot \text{cm}$ )
- ▶ Void-less
- ▶ Superior flatness
- ▶ Superior reliability of Cap plating on AE series

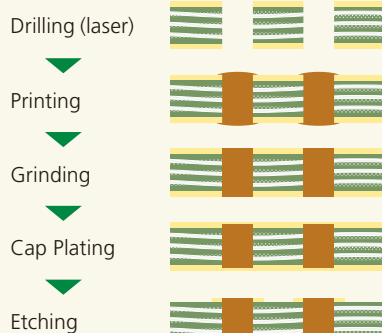
### Structure



### Properties & Characteristic

	Long Life type <b>AE2217</b>	Standard type <b>AE1244</b>
Filler	Silver coating Copper powder	Silver coating Copper powder
Binder	Epoxy resin (2packed type)	Epoxy resin (1packed type)
Solvent	Non	Non
Viscosity (BH type) [Pa·s]	200	110
Curing condition	Pre-heat	40°C/30min+80°C/60min
	Post cure	160°C/60min
Volume resistivity [ $\Omega \cdot \text{cm}$ ]	$1.0 \times 10^{-4}$	$1.0 \times 10^{-4}$
Glass coefficient (DMA) [°C]	113	110
CTE	$\alpha_2$ [ppm]	63
	$\alpha_2$ [ppm]	91
Thermal conductivity [W/mK]	13.5	11.7
Peel strength (Non-desmear) [N/cm]	4.5	4.8

### Process



### Environmental test

	Long Life type <b>AE2217</b>		Standard type <b>AE1244</b>	
Test items (FR-4, 1.0mmt, 0.35mm $\phi$ )	De-lamination & Expansion	Via resistance (m $\Omega$ /via)	De-lamination & Expansion	Via resistance (m $\Omega$ /via)
	Normal state	15	Nothing	15
Solder dip (288°C/10sec/3cycles)	Nothing	13	Nothing	13
Thermal cycling (-65°C/30min $\leftrightarrow$ 125°C/30min/1000cycles)	Nothing	8	Nothing	8
PCT (121°C/2atm/100%RH/336h)	Nothing	8	Nothing	8

\*The date shown above is reference purpose only.

OS1304-1000